## 2SD1746

## Silicon NPN epitaxial planar type

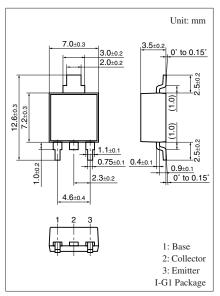
For power switching Complementary to 2SB1176

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Satisfactory liniarity of forward current transfer ratio h<sub>FE</sub>
- Large collector current I<sub>C</sub>
- I type package enabling direct soldering of the radiating fin to the printed circuit board, etc. of small electronic equipment

### ■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	130	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	80	V
Emitter-base voltage (Collector open)	$V_{EBO}$	7	V
Collector current	$I_C$	5	A
Peak collector current	$I_{CP}$	10	A
Collector power dissipation	P <sub>C</sub>	15	W
$T_a = 25^{\circ}C$		1.3	
Junction temperature	$T_j$	150	°C
Storage temperature	T <sub>stg</sub>	-55 ~ +150	°C



Note) Self-supported type package is also prepared.

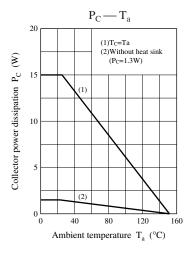
### ■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

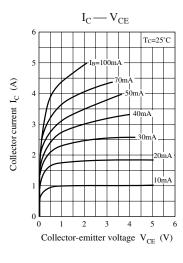
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 10 \text{ mA}, I_B = 0$	80			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 100 \text{ V}, I_{E} = 0$			10	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 5 \text{ V}, I_{C} = 0$			50	μΑ
Forward current transfer ratio	h <sub>FE1</sub>	$V_{CE} = 2 \text{ V}, I_{C} = 0.1 \text{ A}$	45			_
	h <sub>FE2</sub> *	$V_{CE} = 2 \text{ V}, I_{C} = 2 \text{ A}$	90		260	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 4 \text{ A}, I_B = 0.2 \text{ A}$			0.5	V
Base-emitter saturation voltage	V <sub>BE(sat)</sub>	$I_C = 4 \text{ A}, I_B = 0.2 \text{ A}$			1.5	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t <sub>on</sub>	$I_C = 2 \text{ A}, I_{B1} = 0.2 \text{ A}, I_{B2} = -0.2 \text{ A}$		0.5		μs
Storage time	t <sub>stg</sub>	$V_{CC} = 50 \text{ V}$		1.5		μs
Fall time	t <sub>f</sub>			0.15		μs

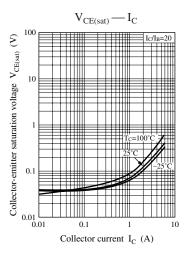
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

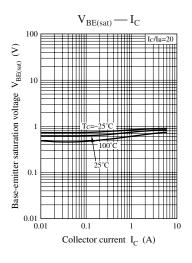
#### 2. \*: Rank classification

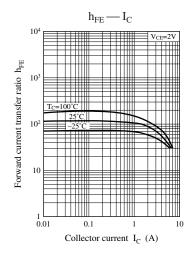
Rank	Q	Р
h <sub>FE2</sub>	90 to 180	130 to 260

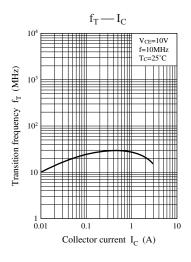


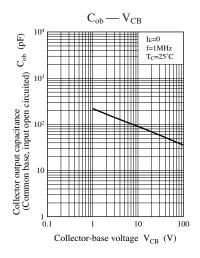


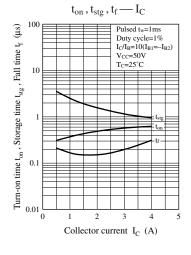


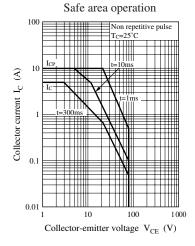


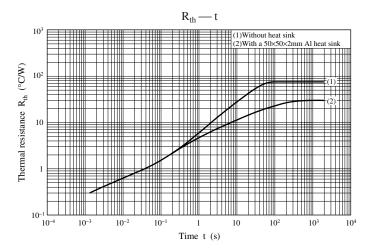












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